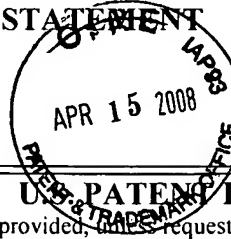


INFORMATION DISCLOSURE STATEMENT BY APPLICANT



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First Named Inventor	John G. DeSteele
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Examiner Name	Jeffrey Thomas Barton

U.S. PATENT DOCUMENTS

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FOREIGN PATENT DOCUMENTS

Examiner's Initials*	Cite No. (optional)	Country	Number	Publication Date	Name of Applicant or Patentee

OTHER DOCUMENTS

Examiner's Initials*	Cite No. (optional)	
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		Final Office action from the U.S. Patent and Trademark Office for U.S. Patent Application No. 10/726,744, dated February 29, 2008.
		International Search Report and Written Opinion for PCT/US2004/040460, filed December 2, 2004 (mailed March 7, 2006).
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